1.	Name of Conveying Party(ies): Shuichi MATSUDA	Please record the attached original documents or copy therew 2. Name and address of receiving party(ies) Name: NEC CORPORATION Address: 7-1, Shiba 5-chome Minato-ku, Tokyo, JAPAN Minato-ku, Tokyo, JAPAN Additional name(s) and address(es) attached? Yes ⊠ No	
4 This	Application number(s) or patent number(s): s document is being filed with a new application, the ex A. Patent Application No(s).	Recution date of the application is: <u>March 25, 2002</u> B. Patent No(s).	
5.	Additional numbers attached? Yes No Name and address of party to whom correspondence concerning document should be mailed: 6. Total number of applications and patents involved: 1		
	Customer No.: <u>000466</u> YOUNG & THOMPSON	 7. Total fee (37 CFR 3.41)\$40.00 2. Enclosed 2. Authorized to be charged to deposit account 8. Deposit Account No. 25-0120 (Attach duplicate copy of this page if paying by 	
	Second Floor 745 South 23 rd Street Arlington, VA 22202		
	Phone: 703-521-2297	deposit account)	
9.	Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Benoit Castel Senoit Castel March 27, 2002		
	Name of Person Signing Signature Total number of pages including cov	Date er sheet, attachments, and documents: <u>2</u>	

REEL: 012744 FRAME: 0909

Deed of Assignment (Before Patent)

ASSIGNMENT

WHEREAS,	SHUICHI MATSUDA						
	of Tokyo, Japan						
hag invented certain new and useful improvements in							
SEMICONDUCTOR DEVICE HAVING	RESIN-SEALED AREA ON CIRCUIT BOARD	THEREOF					
for whichI <u>am about to m</u> (1/we h	akeave made—or am/are about to make)	application for Letters					

Patent of the United States of America;

AND WHEREAS,NEC Corporation, 7-1, Shiba 5-chome,							
Minato-ku	<u>. Tokyo, Japan</u>	is					
desirous of acquiring an interest therein an	nd in the Letters Patent to	be obtained therefor from the					
United States:							

as fully set forth and described in the:

IN TESTIMONY WHEREOF, __I__ hereunto set _my__ hand ___ and affix _my__ seal ___ at ______ Tokyo, Japan_______ this ____25th____ day of ____March_____, A.D. 2002______

huichi Malsuda (Inventor's full Signature) SHUICHI MATSUDA

REEL: 012744 FRAME: 0910

Witness: achi Uka

* State whether the full and exclusive right, or what part of the whole interest is assigned **PATENT**

RECORDED: 03/27/2002